

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJAB55P03
Package Type :	PDFNWB3.3x3.3-8L

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100.00%	1.709%
Lead Frame	Cu	7440-50-8	97.03%	43.6743%
	Fe	7439-89-6	2.21%	
	Pb	7439-92-1	0.01%	
	P	7723-14-0	0.08%	
	Zn	7440-66-6	0.02%	
	Ag	7440-22-4	0.66%	
Die Attach	Ag>= 99,9 %, 粉末状 (>100nm<1mm)	7440-22-4	85.87%	7.9848%
	二乙二醇丁醚醋酸酯	124-17-4	5.40%	
	从 C36-烯化二胺和顺丁烯二酸酐得到的	682800-79-9	3.00%	
	丙烯酸酯单体	Trade Secret	1.60%	
	丙烯酸[2-(1,2-环己基二羧基亚氨基)乙基]	106646-48-4	1.30%	
	(甲基)丙烯酸双环戊烯基氧化乙酯	68586-19-6	1.90%	
	环氧环己烷乙基三甲氧基硅烷	543576	0.45%	
	过氧化二异丙苯	80-43-3	0.29%	
Wire	钯(2+) 盐	1947330-20-2	0.19%	1.4716%
	copper	7440-50-8	99.99%	
	others	/	0.01%	
Mold Compound	Silica	60676-86-0	85.00%	35.2718%
	Epoxy Resin	85954-11-6	8.50%	
	Phenol Resin	29690-82-2	6.00%	
	Carbon Black	1333-86-4	0.50%	
Plating	Tin	7440-31-5	100.00%	9.8884%

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.